



PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of: )  
 )  
Shriram Ramanathan et al. )  
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Serial No.: 10/611,395 )  
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Filed: June 30, 2003 )  
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For: Methods for Bonding Wafers )  
Using a Metal Interlayer )  
 )  
Examiner: N. Berezny )  
 )  
Group Art Unit: 2813 )  
 )  
Attorney Docket No.: P16666 )  
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Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

**PRELIMINARY AMENDMENT**

Sir:

This Preliminary Amendment accompanies a Request for Continued Examination  
(RCE) filed in accordance with 37 C.F.R. § 1.114.

### **INTRODUCTORY COMMENTS**

The following amendments and remarks are proposed in response to the Final Office Action mailed January 7, 2005.

Claims 1-42 were pending in the application, but claims 28-42 have been withdrawn from further consideration. Claims 1-11 and 13-26 have been rejected, and claims 12 and 27 stand objected to. Applicants propose herein to amend claims 1-5, 7-13, 20, 22, 24, and 27. Applicants note that the amendments to each of claims 2-5, 7-12, 20, 22, 24, and 27 was simply to correct matters of form.

Applicants respectfully request reconsideration of the application in view of the amendments set forth herein and the accompanying remarks.